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Abstract: The ability to **UV** cure epoxy (cationically) was developed some 15-20 years ago. An interesting and useful phenomenon of this chemistry is "dark cure". This means that once the photoinitator system is activated by long wave **UV** light, the reaction continues, even if the **UV** light is removed and even in the dark. This is not to be confused with "shadow cure", which means the cure is effected in the shadow areas, where the **UV** light is very low or nonexistent and usually by pre-application of a catalyst, often called a primer or activator. This article looks at the applications of **UV** cure epoxies for electronic encapsulation, including conformal coatings, plastic package sealing, **glob top** and chip underfill encapsulation, and also looks at the materials and their chemistries. (0 Refs)

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Identifiers: **UV** cure epoxies; electronic encapsulation; **UV** cure epoxy; cationic curing; dark cure chemistry; photoinitator system; long wave **UV** light activation; **UV** light; shadow cure; catalyst; cure primer; cure activator; conformal coatings; plastic package sealing; chip underfill encapsulation; **glob top** encapsulation; material chemistries